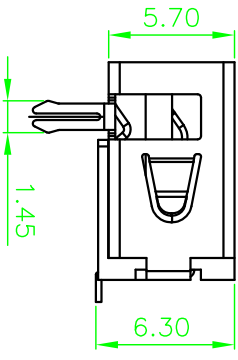
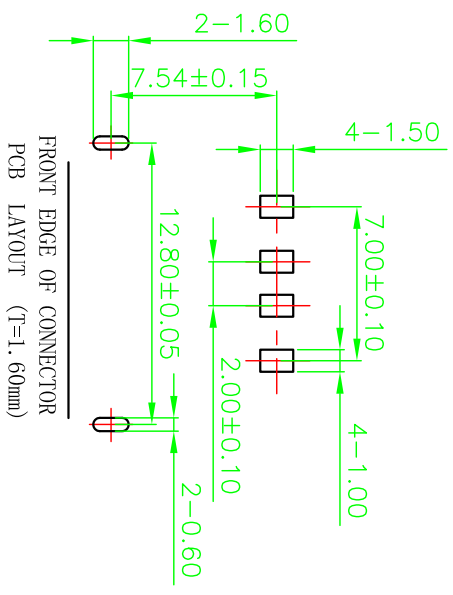
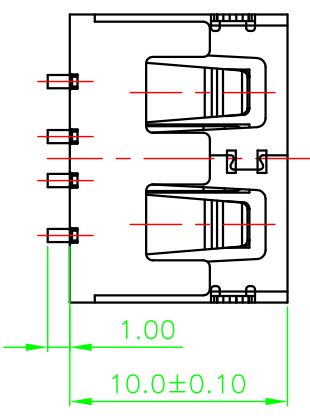
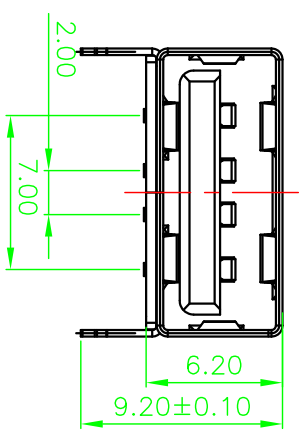
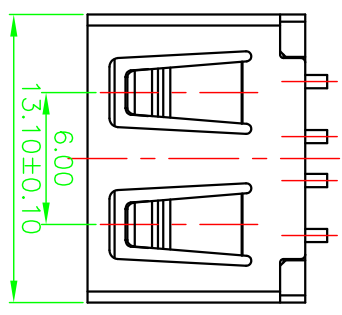


ROHS



Autodesk 教育版产品制作

MAPX

MODIFICATION

DATE

Note:

1. Material:
 - 1.1. Housing: High temperature thermoplastic with/black G/F, UL94v-0
 - 1.2. Contact: copper alloy, t=0.25mm
 - 1.3. Shell: copper/Ferroalloy alloy, t=0.30mm
2. Specification:
 - 2.1. Current rating: 1.5A Max.
 - 2.2. Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3. Contact resistance: 30 mΩ Max.
 - 2.4. Insulation resistance: 100 MΩ Min.
 - 2.5. Total mating force: 3.57 Kgf Max.
 - 2.6. Total unmating force: 1.0 Kgf Min.
3. Finish:
 - 3.1. Contact: Plated Gold in Mating Area; Tin On Solder Tails
 - Shell: Nickel Plating
4. Environmental:
 - 4.1. Temperature range: -55°C~85°C

产品图

深圳市精拓金电子有限公司

公差一览表

TOLERANCE UNLESS OTHERWISE	
X	±0.35
.X	±0.20
.XX	±0.10
.XXX	±0.05

单位	MM	制图	许榕强	制料号
比例	1:1	审核	郭治富	产品名称
日期	2016-09-09	核准	黄国荣	USB AF-SMT C款 反向 前四脚
DATE		APPR		无边 116.2mm
		角法		版本
				A0

1 2 3 4 7 8 9 10

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